

**REVISIONS**

LTR	DESCRIPTION	DATE (YR-MO-DA)	APPROVED
A	Make change to the Common mode supply voltage maximum limit from +80 V to +65 V as specified under paragraph 1.3, 1.4 and Table I. - ro	20-07-28	J. ESCHMEYER
B	Add RHA designator "L" device requirements. - ro	20-09-03	J. ESCHMEYER



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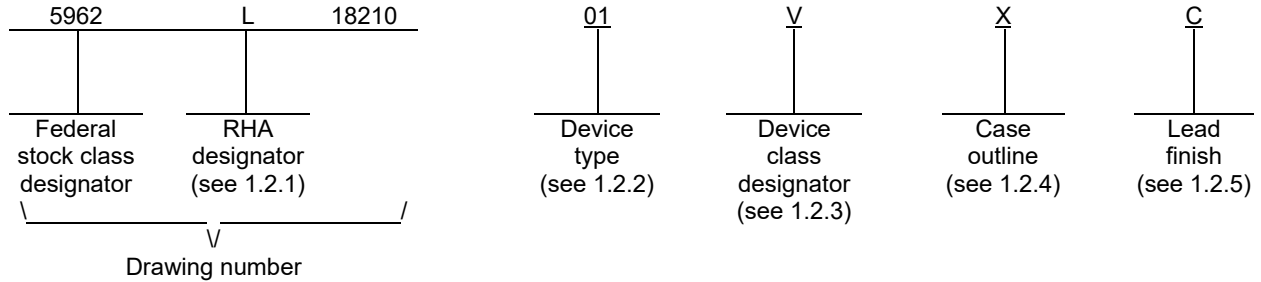
REV STATUS	REV	B	B	B	B	B	B	B	B	B	B	B	B	B	B	B	B	
OF SHEETS	SHEET	1	2	3	4	5	6	7	8	9	10	11	12	13				

PMIC N/A	PREPARED BY RICK OFFICER	<p align="center"><b>DLA LAND AND MARITIME</b>  <b>COLUMBUS, OHIO 43218-3990</b>  <a href="https://www.dla.mil/landandmaritime">https://www.dla.mil/landandmaritime</a></p>																	
<p align="center"><b>STANDARD MICROCIRCUIT DRAWING</b></p> <p>THIS DRAWING IS AVAILABLE FOR USE BY ALL DEPARTMENTS AND AGENCIES OF THE DEPARTMENT OF DEFENSE</p> <p align="center">AMSC N/A</p>	CHECKED BY RAJESH PITHADIA																		
	APPROVED BY CHARLES F. SAFFLE	<p align="center">MICROCIRCUIT, LINEAR, VOLTAGE OUTPUT, UNIDIRECTIONAL MEASUREMENT CURRENT SHUNT MONITOR, MONOLITHIC SILICON</p>																	
	DRAWING APPROVAL DATE 19-01-10																		
	REVISION LEVEL B		<table border="1"> <tr> <td>SIZE A</td> <td>CAGE CODE <b>67268</b></td> <td><b>5962-18210</b></td> </tr> </table>	SIZE A	CAGE CODE <b>67268</b>	<b>5962-18210</b>													
SIZE A	CAGE CODE <b>67268</b>	<b>5962-18210</b>																	
		SHEET	1 OF 13																

1. SCOPE

1.1 Scope. This drawing documents two product assurance class levels consisting of high reliability (device class Q) and space application (device class V). A choice of case outlines and lead finishes are available and are reflected in the Part or Identifying Number (PIN). When available, a choice of Radiation Hardness Assurance (RHA) levels is reflected in the PIN.

1.2 PIN. The PIN is as shown in the following example:



1.2.1 RHA designator. Device classes Q and V RHA marked devices meet the MIL-PRF-38535 specified RHA levels and are marked with the appropriate RHA designator. A dash (-) indicates a non-RHA device.

1.2.2 Device type(s). The device type(s) identify the circuit function as follows:

<u>Device type</u>	<u>Generic number</u>	<u>Circuit function</u>
01	INA901-SP	Voltage output, unidirectional measurement current shunt monitor

1.2.3 Device class designator. The device class designator is a single letter identifying the product assurance level as follows:

<u>Device class</u>	<u>Device requirements documentation</u>
Q or V	Certification and qualification to MIL-PRF-38535

1.2.4 Case outline(s). The case outline(s) are as designated in MIL-STD-1835 and as follows:

<u>Outline letter</u>	<u>Descriptive designator</u>	<u>Terminals</u>	<u>Package style</u>
X	See figure 1	8	Ceramic flatpack

1.2.5 Lead finish. The lead finish is as specified in MIL-PRF-38535 for device classes Q and V.

<b>STANDARD MICROCIRCUIT DRAWING</b> DLA LAND AND MARITIME COLUMBUS, OHIO 43218-3990	SIZE <b>A</b>		<b>5962-18210</b>
		REVISION LEVEL <b>B</b>	SHEET <b>2</b>

1.3 Absolute maximum ratings. 1/

Supply voltage (Vs) .....	+18 V
Analog inputs (+VIN, -VIN):	
Differential (+VIN - -VIN) .....	-18 V to +18 V
Common mode .....	-16 V to +65 V
Analog output: OUT and PRE OUT pins .....	GND – 0.3 V to +Vs + 0.3 V
Input current into any pin .....	5 mA maximum
Junction temperature (Tj) .....	+150°C
Storage temperature range .....	-65°C to +150°C
Electrostatic discharge (ESD) rating:	
Human body model (HBM) per JEDEC JS-001 .....	±1000 V 2/
Charge device model (CDM) per JESD22-C101 .....	±500 V 3/

1.4 Recommended operating conditions.

Operating supply voltage .....	2.7 V to 16 V
Common mode input voltage (VCM) .....	-15 V to +65 V
Operating free air temperature range (TA) .....	-55°C to +125°C

1.5 Radiation features.

Maximum total dose available (effective dose rate = 30mrad(Si)/s) .....	50 krads(Si) 4/
Maximum total dose available (low dose rate ≤ 10 mrad(Si)/s) .....	50 krads(Si) 5/

1.6 Thermal characteristics.

Thermal metric	Symbol	Case X	Unit
Thermal resistance, junction-to-ambient	$\theta_{JA}$	116.7	°C/W
Thermal resistance, junction-to-case (top)	$\theta_{JC(TOP)}$	39.1	°C/W
Thermal resistance, junction-to-board	$\theta_{JB}$	98.8	°C/W
Characterization parameter, junction-to-top	$\psi_{JT}$	32.5	°C/W
Characterization parameter, junction-to-board	$\psi_{JB}$	93.1	°C/W
Thermal resistance, junction-to-case (bottom)	$\theta_{JC(BOT)}$	26.5	°C/W

- 1/ Stresses above the absolute maximum rating may cause permanent damage to the device. Extended operation at the maximum levels may degrade performance and affect reliability.
- 2/ JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
- 3/ JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.
- 4/ Device type 01 is irradiated at a dose rate = 50 - 300 rad(Si)/s in accordance with MIL-STD-883, method 1019, condition A, to a maximum total ionizing dose as specified. The effective dose rate for device type 01 after extended room temperature anneal = 30mrad(Si)/s per MIL-STD-883, method 1019, condition A section 3.11.2. The total dose specification for these devices only applies to the specified effective dose rate, or lower environment.
- 5/ The manufacturer supplying device type 01 also tested low dose rate condition D in accordance to MIL-STD-883 method 1019. The radiation end point limit noted parameters are guaranteed only for the conditions as specified in MIL-STD-883, method 1019, condition D to a maximum total dose of 50 krads(Si).

<b>STANDARD MICROCIRCUIT DRAWING</b> DLA LAND AND MARITIME COLUMBUS, OHIO 43218-3990	SIZE <b>A</b>		<b>5962-18210</b>
		REVISION LEVEL <b>B</b>	SHEET <b>3</b>

2. APPLICABLE DOCUMENTS

2.1 Government specification, standards, and handbooks. The following specification, standards, and handbooks form a part of this drawing to the extent specified herein. Unless otherwise specified, the issues of these documents are those cited in the solicitation or contract.

DEPARTMENT OF DEFENSE SPECIFICATION

MIL-PRF-38535 - Integrated Circuits, Manufacturing, General Specification for.

DEPARTMENT OF DEFENSE STANDARDS

MIL-STD-883 - Test Method Standard Microcircuits.  
 MIL-STD-1835 - Interface Standard Electronic Component Case Outlines.

DEPARTMENT OF DEFENSE HANDBOOKS

MIL-HDBK-103 - List of Standard Microcircuit Drawings.  
 MIL-HDBK-780 - Standard Microcircuit Drawings.

(Copies of these documents are available online at <https://quicksearch.dla.mil>.)

2.2 Non-Government publications. The following document(s) form a part of this document to the extent specified herein. Unless otherwise specified, the issues of these documents are those cited in the solicitation or contract.

JEDEC Solid State Technology Association

JEDEC JS-001 - Human Body Model Testing of Integrated Circuits  
 JESD22-C101 - Field-Induced Charged-Device Model Test Method for Electrostatic-Discharge-Withstand Thresholds of Microelectronics Components  
 JEDEC JEP 155 - Recommended ESD Target Levels for HBM/MM Qualification  
 JEDEC JEP 157 - Recommended ESD-CDM Target Levels

(Copies of these documents are available online at <https://www.jedec.org>.)

2.3 Order of precedence. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing takes precedence. Nothing in this document, however, supersedes applicable laws and regulations unless a specific exemption has been obtained.

3. REQUIREMENTS

3.1 Item requirements. The individual item requirements for device classes Q and V shall be in accordance with MIL-PRF-38535 as specified herein, or as modified in the device manufacturer's Quality Management (QM) plan. The modification in the QM plan shall not affect the form, fit, or function as described herein.

3.2 Design, construction, and physical dimensions. The design, construction, and physical dimensions shall be as specified in MIL-PRF-38535 and herein for device classes Q and V.

3.2.1 Case outline. The case outline shall be in accordance with 1.2.4 herein and figure 1.

3.2.2 Terminal connections. The terminal connections shall be as specified on figure 2.

3.2.3 Block diagram. The block diagram shall be as specified on figure 3.

3.2.4 Radiation exposure circuit. The radiation exposure circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing and acquiring activity upon request.

3.3 Electrical performance characteristics and postirradiation parameter limits. Unless otherwise specified herein, the electrical performance characteristics and postirradiation parameter limits are as specified in table I and shall apply over the full ambient operating temperature range.

3.4 Electrical test requirements. The electrical test requirements shall be the subgroups specified in table IIA. The electrical tests for each subgroup are defined in table I.

<b>STANDARD                  MICROCIRCUIT DRAWING</b> DLA LAND AND MARITIME COLUMBUS, OHIO 43218-3990	SIZE <b>A</b>		<b>5962-18210</b>
		REVISION LEVEL <b>B</b>	SHEET <b>4</b>

TABLE I. Electrical performance characteristics.

Test	Symbol	Conditions <u>1/ 2/ 3/</u> -55°C ≤ T <sub>A</sub> ≤ +125°C unless otherwise specified	Group A subgroups	Device type	Limits		Unit
					Min	Max	
Input							
Full scale input voltage	V <sub>SENSE</sub>	V <sub>SENSE</sub> = +V <sub>IN</sub> - -V <sub>IN</sub>	1,2,3	01		V <sub>S</sub> - 0.2/ Gain	V
Common mode input range	V <sub>CM</sub>		1,2,3	01	-16	+65	V
Common mode rejection ratio	CMRR	+V <sub>IN</sub> = -16 V to +80 V	1	01	80		dB
			2,3		70		
Offset voltage, referred to input (RTI)	V <sub>OS</sub>		1	01		±2.5	mV
			2,3			±3.5	
Offset voltage versus power supply	PSR	V <sub>S</sub> = 2.7 V to +18 V, V <sub>CM</sub> = +18 V	1,2,3	01		250	μV/V
Input bias current	I <sub>B</sub>		1	01		±16	μA
			2,3			±19	
Output (V <sub>SENSE</sub> ≥ 20 mV)							
Total gain error		V <sub>SENSE</sub> = 20 mV to 100 mV	4,5,6	01		±1.5	%
Total output error <u>4/</u>			4	01		±2.0	%
			5,6			±3.0	
Voltage output <span style="float: right;">R<sub>L</sub> = 10 kΩ to GND</span>							
Swing to +V power supply rail	SwV <sub>CC</sub>		1,2,3	01		+V - 0.2	V
Swing to GND			1,2,3	01		V <sub>GND</sub> + 0.05	V

See footnotes at end of table.

**STANDARD  
MICROCIRCUIT DRAWING**  
DLA LAND AND MARITIME  
COLUMBUS, OHIO 43218-3990

SIZE  
**A**

REVISION LEVEL  
**B**

**5962-18210**

SHEET  
**5**

TABLE I. Electrical performance characteristics - continued.

Test	Symbol	Conditions <u>1/ 2/ 3/</u> -55°C ≤ T <sub>A</sub> ≤ +125°C unless otherwise specified	Group A subgroups	Device type	Limits		Unit
					Min	Max	
Power supply							
Operating range	V <sub>S</sub>		1,2,3	01	+2.7	+16	V
Quiescent current	I <sub>Q</sub>	V <sub>OUT</sub> = 2 V	1	01		900	μA
			2,3			1200	
		V <sub>SENSE</sub> = 0 mV	1			500	
			2,3			650	

- 1/ Unless otherwise specified, V<sub>S</sub> = 2.7 V – 16 V, V<sub>CM</sub> = +12 V, V<sub>SENSE</sub> = 100 mV, and PRE OUT connected BUF IN.
- 2/ Device type 01 is irradiated at a dose rate = 50 - 300 rad(Si)/s in accordance with MIL-STD-883, method 1019, condition A, and is guaranteed, to a maximum total dose specified. The effective dose rate for device type 01 after extended room temperature anneal = 30 mrad(Si)/s per MIL-STD-883, method 1019, condition A, section 3.11.2. The total dose specification for these devices only applies to the specified effective dose rate, or lower environment.
- 3/ The manufacturer supplying device type 01 also tested low dose rate condition D in accordance to MIL-STD-883 method 1019. The radiation end point limits for the noted parameters are guaranteed only for the conditions as specified in MIL-STD-883, method 1019, condition D to a maximum total dose of 50 krad(Si).
- 4/ Total output error includes effects of gain error and V<sub>OS</sub>.

3.5 Marking. The part shall be marked with the PIN listed in 1.2 herein. In addition, the manufacturer's PIN may also be marked. For packages where marking of the entire SMD PIN number is not feasible due to space limitations, the manufacturer has the option of not marking the "5962-" on the device. For RHA product using this option, the RHA designator shall still be marked. Marking for device classes Q and V shall be in accordance with MIL-PRF-38535.

3.5.1 Certification/compliance mark. The certification mark for device classes Q and V shall be a "QML" or "Q" as required in MIL-PRF-38535.

3.6 Certificate of compliance. For device classes Q and V, a certificate of compliance shall be required from a QML-38535 listed manufacturer in order to supply to the requirements of this drawing (see 6.6.1 herein). The certificate of compliance submitted to DLA Land and Maritime-VA prior to listing as an approved source of supply for this drawing shall affirm that the manufacturer's product meets, for device classes Q and V, the requirements of MIL-PRF-38535 and herein.

3.7 Certificate of conformance. A certificate of conformance as required for device classes Q and V in MIL-PRF-38535 shall be provided with each lot of microcircuits delivered to this drawing.

<b>STANDARD MICROCIRCUIT DRAWING</b> DLA LAND AND MARITIME COLUMBUS, OHIO 43218-3990	SIZE <b>A</b>		<b>5962-18210</b>
		REVISION LEVEL <b>B</b>	SHEET <b>6</b>

Case X

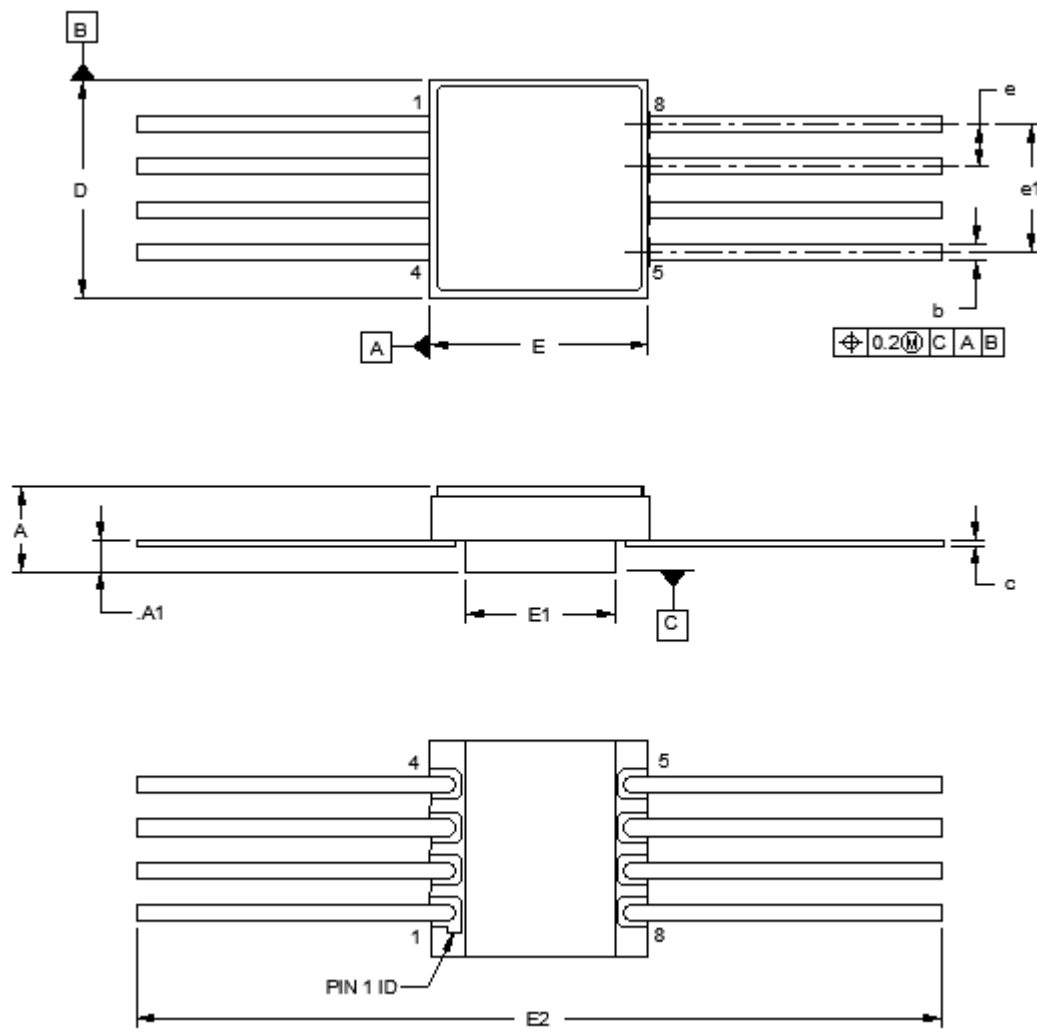


FIGURE 1. Case outline.

<b>STANDARD MICROCIRCUIT DRAWING</b> DLA LAND AND MARITIME COLUMBUS, OHIO 43218-3990	SIZE <b>A</b>		<b>5962-18210</b>
		REVISION LEVEL <b>B</b>	SHEET <b>7</b>

Case X – continued.

Symbol	Dimensions			
	Inches		Millimeters	
	Min	Max	Min	Max
A	---	.1096	---	2.785
A1	---	.0374	---	0.95
b	.0165	.0204	0.42	0.52
c	.0047	.0078	0.12	0.20
D	.2450	.2647	6.225	6.725
E	.2454	.2651	6.235	6.735
E1	.1749 NOM		4.445 NOM	
E2	---	.9448	---	24
e	.0499 BSC		1.27 BSC	
e1	.1499 BSC		3.81 BSC	
n	8		8	

NOTES:

1. Controlling dimensions are millimeter, inch dimensions are given for reference only.
2. This package is hermetically sealed with a metal lid. The lid is not connected to any lead.
3. The leads are gold plated.

FIGURE 1. Case outline - continued.

<b>STANDARD MICROCIRCUIT DRAWING</b> DLA LAND AND MARITIME COLUMBUS, OHIO 43218-3990	SIZE <b>A</b>		<b>5962-18210</b>
		REVISION LEVEL <b>B</b>	SHEET 8



Device type	01		
Case outline	X		
Terminal number	Terminal symbol	I/O	Description
1	-IN	Analog input	Connect to load side of shunt resistor.
2	GND	Ground	Ground.
3	PRE OUT	Analog output	Connect to input of filter to BUF IN.
4	BUF IN	Analog input	Connect to output of filter from PRE OUT.
5	OUT	Analog output	Output voltage.
6	+VS	Power supply	Power supply, +2.7 V to +16 V.
7	NC	---	Connect to ground. No internal connection.
8	+IN	Analog input	Connect to supply side of shunt resistor.

FIGURE 2. Terminal connections.

<b>STANDARD MICROCIRCUIT DRAWING</b> DLA LAND AND MARITIME COLUMBUS, OHIO 43218-3990	SIZE <b>A</b>		<b>5962-18210</b>
		REVISION LEVEL <b>B</b>	SHEET <b>9</b>

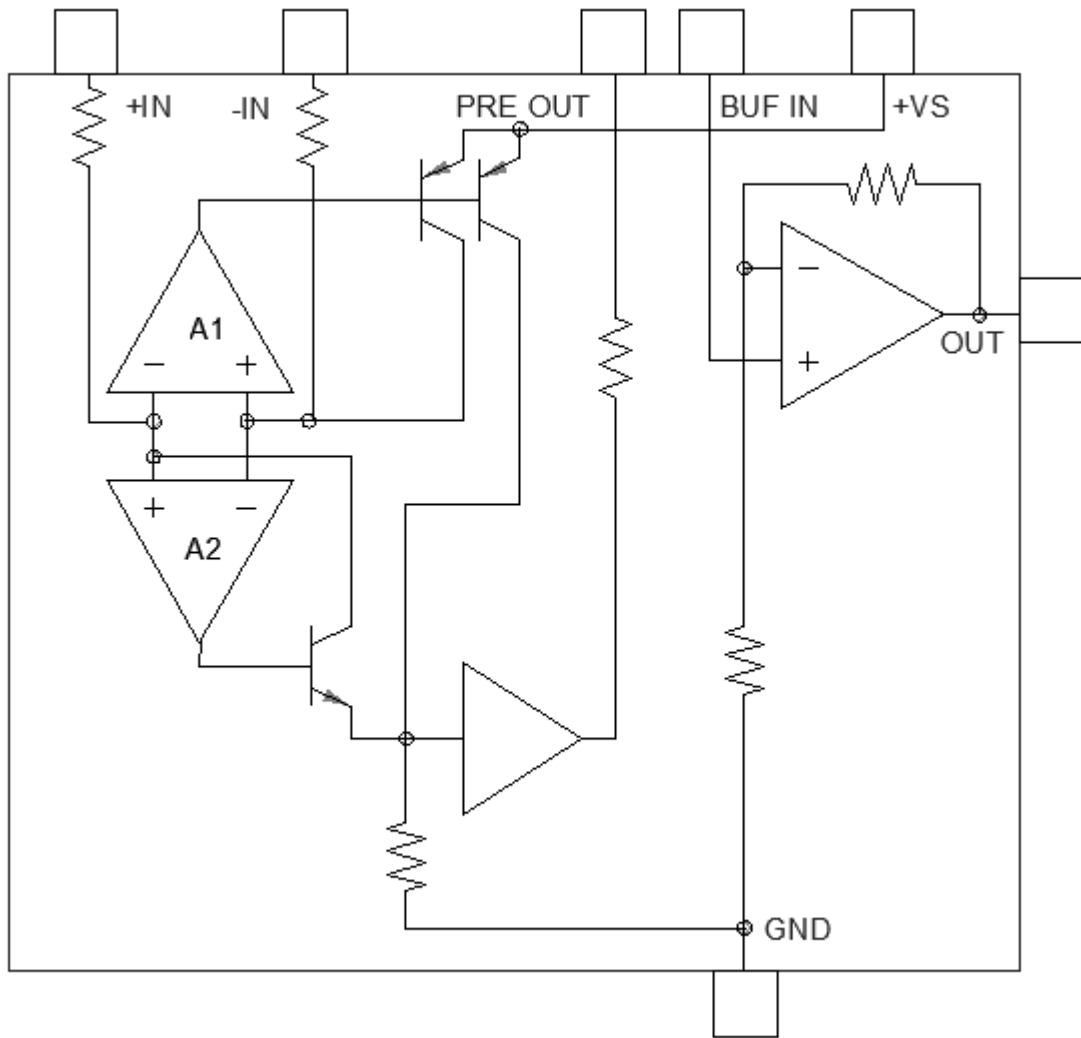


FIGURE 3. Block diagram.

**STANDARD  
MICROCIRCUIT DRAWING**  
DLA LAND AND MARITIME  
COLUMBUS, OHIO 43218-3990

SIZE  
**A**

REVISION LEVEL  
**B**

**5962-18210**

SHEET  
10

#### 4. VERIFICATION

4.1 Sampling and inspection. For device classes Q and V, sampling and inspection procedures shall be in accordance with MIL-PRF-38535 or as modified in the device manufacturer's Quality Management (QM) plan. The modification in the QM plan shall not affect the form, fit, or function as described herein.

4.2 Screening. For device classes Q and V, screening shall be in accordance with MIL-PRF-38535, and shall be conducted on all devices prior to qualification and technology conformance inspection.

##### 4.2.1 Additional criteria for device classes Q and V.

- a. The burn-in test duration, test condition and test temperature, or approved alternatives shall be as specified in the device manufacturer's QM plan in accordance with MIL-PRF-38535. The burn-in test circuit shall be maintained under document revision level control of the device manufacturer's Technology Review Board (TRB) in accordance with MIL-PRF-38535 and shall be made available to the acquiring or preparing activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in method 1015 of MIL-STD-883.
- b. Interim and final electrical test parameters shall be as specified in table IIA herein.
- c. Additional screening for device class V beyond the requirements of device class Q shall be as specified in MIL-PRF-38535, appendix B.

4.3 Qualification inspection for device classes Q and V. Qualification inspection for device classes Q and V shall be in accordance with MIL-PRF-38535. Inspections to be performed shall be those specified in MIL-PRF-38535 and herein for groups A, B, C, D, and E inspections (see 4.4.1 through 4.4.4).

4.4 Conformance inspection. Technology conformance inspection for classes Q and V shall be in accordance with MIL-PRF-38535 including groups A, B, C, D, and E inspections, and as specified herein.

##### 4.4.1 Group A inspection.

- a. Tests shall be as specified in table IIA herein.
- b. Subgroups 7, 8, 9, 10, and 11 in table I, method 5005 of MIL-STD-883 shall be omitted.

<b>STANDARD MICROCIRCUIT DRAWING</b> DLA LAND AND MARITIME COLUMBUS, OHIO 43218-3990	SIZE <b>A</b>		<b>5962-18210</b>
		REVISION LEVEL <b>B</b>	SHEET 11

TABLE IIA. Electrical test requirements.

Test requirements	Subgroups (in accordance with MIL-PRF-38535, table III)	
	Device class Q	Device class V
Interim electrical parameters (see 4.2)	1,2,3,4,5,6	1,2,3,4,5,6
Final electrical parameters (see 4.2)	1,2,3,4,5,6 <u>1/</u>	1,2,3, <u>1/ 2/</u> 4,5,6
Group A test requirements (see 4.4)	1,2,3,4,5,6	1,2,3,4,5,6
Group C end-point electrical parameters (see 4.4)	1,2,3,4,5,6	1,2,3, <u>2/</u> 4,5,6
Group D end-point electrical parameters (see 4.4)	1,4	1,4
Group E end-point electrical parameters (see 4.4)	1	1

1/ PDA applies to subgroup 1.

2/ Delta limits as specified in table IIB shall be required where specified, and the delta limits shall be computed with reference to the previous electrical parameters.

TABLE IIB. Burn-in and operating life test delta parameters.  $T_A = +25^\circ\text{C}$ .

Parameters	Symbol	Conditions	Device type	Limit
Input bias current	I <sub>B</sub>		01	±750 nA
Quiescent current	I <sub>Q</sub>	V <sub>OUT</sub> = 2 V	01	±45 µA
		V <sub>SENSE</sub> = 0 mV		±90 µA
Swing to +V power supply rail	SWVCC		01	±118 mV

**STANDARD  
MICROCIRCUIT DRAWING**  
DLA LAND AND MARITIME  
COLUMBUS, OHIO 43218-3990

SIZE  
**A**

**5962-18210**

REVISION LEVEL  
**B**

SHEET

12

4.4.2 Group C inspection. The group C inspection end-point electrical parameters shall be as specified in table IIA herein.

4.4.2.1 Additional criteria for device classes Q and V. The steady-state life test duration, test condition and test temperature, or approved alternatives shall be as specified in the device manufacturer's QM plan in accordance with MIL-PRF-38535. The test circuit shall be maintained under document revision level control by the device manufacturer's TRB in accordance with MIL-PRF-38535 and shall be made available to the acquiring or preparing activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in method 1005 of MIL-STD-883.

4.4.3 Group D inspection. The group D inspection end-point electrical parameters shall be as specified in table IIA herein.

4.4.4 Group E inspection. Group E inspection is required only for parts intended to be marked as radiation hardness assured (see 3.5 herein).

- a. End-point electrical parameters shall be as specified in table IIA herein.
- b. For device classes Q and V, the devices or test vehicle shall be subjected to radiation hardness assured tests as specified in MIL-PRF-38535 for the RHA level being tested. All device classes must meet the postirradiation end-point electrical parameter limits as defined in table I at  $T_A = +25^{\circ}\text{C} \pm 5^{\circ}\text{C}$ , after exposure, to the subgroups specified in table IIA herein.

4.4.4.1 Total dose irradiation testing. Total dose irradiation testing shall be performed in accordance with MIL-STD-883 method 1019, condition A and condition D and as specified herein (see 1.5).

## 5. PACKAGING

5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-PRF-38535 for device classes Q and V.

## 6. NOTES

6.1 Intended use. Microcircuits conforming to this drawing are intended for use for Government microcircuit applications (original equipment), design applications, and logistics purposes.

6.1.1 Replaceability. Microcircuits covered by this drawing will replace the same generic device covered by a contractor prepared specification or drawing.

6.2 Configuration control of SMD's. All proposed changes to existing SMD's will be coordinated with the users of record for the individual documents. This coordination will be accomplished using DD Form 1692, Engineering Change Proposal.

6.3 Record of users. Military and industrial users should inform DLA Land and Maritime when a system application requires configuration control and which SMD's are applicable to that system. DLA Land and Maritime will maintain a record of users and this list will be used for coordination and distribution of changes to the drawings. Users of drawings covering microelectronic devices (FSC 5962) should contact DLA Land and Maritime-VA, telephone (614) 692-8108.

6.4 Comments. Comments on this drawing should be directed to DLA Land and Maritime-VA, Columbus, Ohio 43218-3990, or telephone (614) 692-0540.

6.5 Abbreviations, symbols, and definitions. The abbreviations, symbols, and definitions used herein are defined in MIL-PRF-38535 and MIL-HDBK-1331.

6.6 Sources of supply.

6.6.1 Sources of supply for device classes Q and V. Sources of supply for device classes Q and V are listed in MIL-HDBK-103 and QML-38535. The vendors listed in MIL-HDBK-103 and QML-38535 have submitted a certificate of compliance (see 3.6 herein) to DLA Land and Maritime-VA and have agreed to this drawing.

<b>STANDARD MICROCIRCUIT DRAWING</b> DLA LAND AND MARITIME COLUMBUS, OHIO 43218-3990	SIZE <b>A</b>		<b>5962-18210</b>
		REVISION LEVEL <b>B</b>	SHEET <b>13</b>

STANDARD MICROCIRCUIT DRAWING BULLETIN

DATE: 20-09-03

Approved sources of supply for SMD 5962-18210 are listed below for immediate acquisition information only and shall be added to MIL-HDBK-103 and QML-38535 during the next revision. MIL-HDBK-103 and QML-38535 will be revised to include the addition or deletion of sources. The vendors listed below have agreed to this drawing and a certificate of compliance has been submitted to and accepted by DLA Land and Maritime-VA. This information bulletin is superseded by the next dated revision of MIL-HDBK-103 and QML-38535. DLA Land and Maritime maintains an online database of all current sources of supply at <https://landandmaritimeapps.dla.mil/programs/smcr/>.

Standard microcircuit drawing PIN <u>1/</u>	Vendor CAGE number	Vendor similar PIN <u>2/</u>
5962-1821001VXC	01295	INA901A-SP
5962L1821001VXC	01295	INA901A-SP

- 1/ The lead finish shown for each PIN representing a hermetic package is the most readily available from the manufacturer listed for that part. If the desired lead finish is not listed contact the vendor to determine its availability.
- 2/ **Caution.** Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.

Vendor CAGE number

01295

Vendor name and address

Texas Instruments, Inc.  
Semiconductor Group  
8505 Forest Lane  
P.O. Box 660199  
Dallas, TX 75243

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